

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A flexible semiconductor device comprising:

a semiconductor substrate defining an active area and having a first surface and a second surface, the first surface being opposite the second surface, wherein the semiconductor substrate is formed from a semiconductor layer;

an integrated circuit provided with a plurality of semiconductor elements located at the active area of the semiconductor substrate at the first surface of the semiconductor substrate, the semiconductor substrate having a suitable thickness so as to be flexible, wherein the plurality of semiconductor elements are interconnected according to a desired pattern in an interconnect structure,

a mask formed over the second surface of the semiconductor

substrate,

a support layer of electrically insulating material, and  
an antenna, which is located laterally outside the active area and is electrically connected to the interconnect structure, the antenna and the integrated circuit being supported by the support layer,

wherein the mask is substantially confined at the active area over the integrated circuit and protects the integrated circuit during removal of portions of the semiconductor layer which are not covered by the mask so that the semiconductor substrate is substantially ~~confined to~~ present in an area including outside of the integrated circuit and adjacent to the integrated circuit, and the semiconductor substrate is absent in areas between the antenna and the integrated circuit.

2. (Previously Presented) The flexible semiconductor device as claimed in Claim 1, wherein the integrated circuit is devoid of any bond pad structures.

Claims 3-4 (Canceled)

5.(Previously Presented) The flexible semiconductor device as claimed in claim 1 wherein the semiconductor substrate is present only in the active area.

6.(Previously Presented) The flexible semiconductor device as claimed in claim 1, wherein the antenna is an inductor suitable for wireless communication.

7.(Previously Presented) The flexible semiconductor device as claimed in claim 6, wherein the integrated circuit is substantially surrounded by the inductor.

Claims 8-20 (Canceled)

21.(Previously Presented) The flexible semiconductor device of claim 1, wherein the antenna and the integrated circuit are on opposite sides of the interconnect structure.